



**Announcement of an IEEE/OSA**  
***Journal of Lightwave Technology* Special Issue on:**  
**MICROWAVE PHOTONICS**

Submission Deadline 1 February 2018  
Publication: October 2018

This special issue covers all topics in the interdisciplinary field of microwave photonics, which will be announced as a special issue for the top conference (MWP'2017) of this field. Microwave photonics is concerned with the use of photonic devices, systems and techniques for applications in microwave, millimeter, and THz wave engineering, and also encompasses the development of high-speed photonic components. The field is experiencing a healthy period of growth, driven by the recent interest in integrated microwave photonics and the development of microwave/millimeter-wave photonics for 5G applications. Feasible topics include (but are not limited to):

- High-speed optoelectronic devices
- Integrated microwave photonics
- Photonic techniques for microwave signal generation and distribution
- Photonic microwave processing, sensing, and measurements
- THz techniques and applications
- Radio over fiber techniques, fiber-wireless communications, and 5G
- Innovative applications of microwave photonics (astronomy, traffic and automotive, electronic warfare, radar, medicine and health care, etc.)

A portion of this issue will feature expanded versions of accepted papers presented at the 2017 International Topical Meeting on Microwave Photonics (MWP 2017) in Beijing, China from 23-17 October, 2017. This meeting included a workshop on hot topics in this field.

On behalf of the Guest Editors and the Editor-in-Chief, we encourage you to submit your paper to the journal. Typically, these papers are 18 pages for the tutorial reviews, 10 pages for invited papers, and 7 pages for the regular papers. Mandatory page charges of \$260USD per page are enforced in excess of 7 pages with accepted papers posted online within 1 week of author final file upload

The Guest Editors for this issue are: **Jianping Yao**, University of Ottawa, Canada; **Jose Capmany**, Polytechnic University of Valencia, Spain; **Hongwei Chen**, Tsinghua University, China; **Xihua Zou**, Southwest Jiaotong University, China.

Submissions by website only: <http://mc.manuscriptcentral.com/jlt-ieee>

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